

ABSTRACT

An image information of a substrate (1) on which a plurality of electronic components (2) are to be mounted is obtained. Next, the image information is binarized by using a predetermined threshold value (TH1), so that binary data are acquired. Then, a tentative presence region recognized as corresponding to the electronic component (2) is acquired on the basis of the binary data. Further, a new threshold value (TH2) is set by changing the predetermined threshold value (TH1). Next, new binary data are acquired by using the new threshold value (TH2). Thereby, a new tentative presence region is acquired. Then, the new tentative presence region is combined with the just preceding tentative presence region. Then, a new threshold value (TH3) is set. A series of above described steps are repeated until all detection results of individual chips (2) indicating whether or not each of the plurality of chips is mounted at a predetermined position, are prepared.